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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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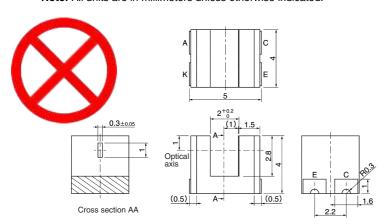
# Photomicrosensor (Transmissive) **FF-SX1108**



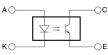
Be sure to read *Precautions* on page 24.

#### Dimensions

Note: All units are in millimeters unless otherwise indicated.

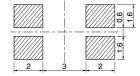


#### Internal Circuit



Terminal No.	Name	
Α	Anode	
K	Cathode	
С	Collector	
E	Emitter	

#### Recommended Soldering Pattern



Unless otherwise specified, the tolerances are  $\pm 0.15$  mm.

#### ■ Features

- Ultra-compact with a 5-mm-wide sensor and a 2-mm-wide slot.
- PCB surface mounting type.
- High resolution with a 0.3-mm-wide aperture.

#### ■ Absolute Maximum Ratings (Ta = 25°C)

	Item	Symbol	Rated value
Emitter	Forward current	l <sub>F</sub>	25 mA (see note 1)
	Pulse forward cur- rent	I <sub>FP</sub>	100 mA (see note 2)
	Reverse voltage	$V_R$	5 V
Detector	Collector–Emitter voltage	V <sub>CEO</sub>	20 V
	Emitter–Collector voltage	V <sub>ECO</sub>	5 V
	Collector current	I <sub>C</sub>	20 mA
	Collector dissipa- tion	P <sub>C</sub>	75 mW (see note 1)
Ambient tem-	Operating	Topr	–30°C to 85°C
perature	Storage	Tstg	–40°C to 90°C
	Reflow soldering	Tsol	255°C (see note 3)
	Manual soldering	Tsol	350°C (see note 3)

**Note: 1.** Refer to the temperature rating chart if the ambient temperature exceeds 25°C.

- 2. Duty: 1/100; Pulse width: 0.1 ms
- 3. Complete soldering within 10 seconds for reflow soldering and within 3 seconds for manual soldering.

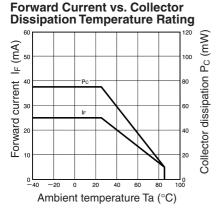
#### ■ Electrical and Optical Characteristics (Ta = 25°C)

	Item	Symbol	Value	Condition
Emitter	Forward voltage	V <sub>F</sub>	1.1 V typ., 1.3 V max.	I <sub>F</sub> = 5 mA
	Reverse current	I <sub>R</sub>	10 μA max.	V <sub>R</sub> = 5 V
	Peak emission wavelength	$\lambda_{P}$	940 nm typ.	I <sub>F</sub> = 20 mA
Detector	Light current	IL	50 μA min., 150 μA typ., 500 μA max.	$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}$
	Dark current	I <sub>D</sub>	100 nA max.	V <sub>CE</sub> = 10 V, 0 ℓx
	Leakage current	I <sub>LEAK</sub>		
	Collector–Emitter saturated voltage	V <sub>CE</sub> (sat)	0.1 V typ., 0.4 V max.	$I_F = 20 \text{ mA}, I_L = 50 \mu\text{A}$
	Peak spectral sensitivity wavelength	$\lambda_{P}$	900 nm typ.	
Rising time		tr	10 μs typ.	$V_{CC} = 5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega,$ $I_{L} = 100 \mu\text{A}$
Falling time		tf	10 μs typ.	$V_{CC} = 5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega,$ $I_{L} = 100 \mu\text{A}$

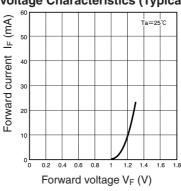
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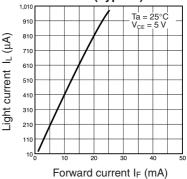
#### ■ Engineering Data



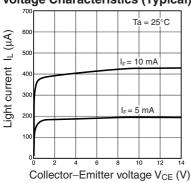
#### Forward Current vs. Forward Voltage Characteristics (Typical)



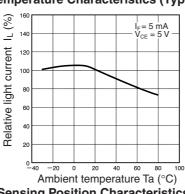
Light Current vs. Forward Current **Characteristics (Typical)** 



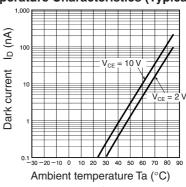
Light Current vs. Collector-Emitter **Voltage Characteristics (Typical)** 



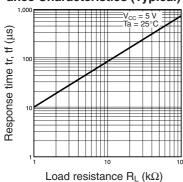
**Relative Light Current vs. Ambient** Temperature Characteristics (Typical) perature Characteristics (Typical)



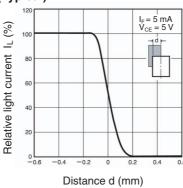
Dark Current vs. Ambient Tem-



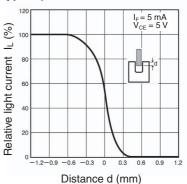
Response Time vs. Load Resistance Characteristics (Typical)



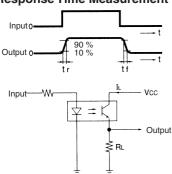
**Sensing Position Characteristics** (Typical)



**Sensing Position Characteristics** (Typical)



**Response Time Measurement Circuit** 



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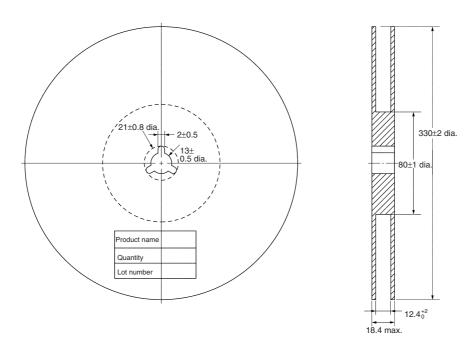
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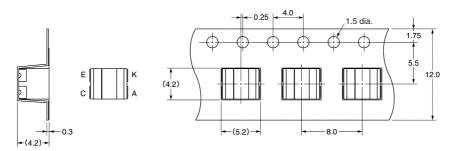
Unit: mm (inch)

# **■** Tape and Reel

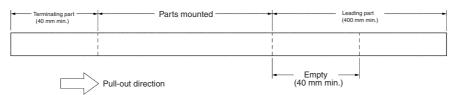
#### Reel



#### **Tape**



## **Tape configuration**



## **Tape quantity**

2,000 pcs./reel

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## **Precautions**

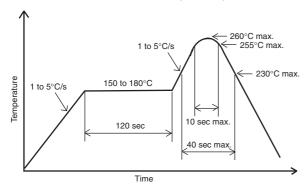
#### **■** Soldering Information

#### Reflow soldering

• The following soldering paste is recommended:

Melting temperature: 216 to 220°C Composition: Sn 3.5 Ag 0.75 Cu

- The recommended thickness of the metal mask for screen printing is between 0.2 and 0.25 mm.
- Set the reflow oven so that the temperature profile shown in the following chart is obtained for the upper surface of the product being soldered.



#### Manual soldering

- Use "Sn 60" (60% tin and 40% lead) or solder with silver content.
- Use a soldering iron of less than 25 W, and keep the temperature of the iron tip at 300°C or below.
- Solder each point for a maximum of three seconds.
- After soldering, allow the product to return to room temperature before handling it.

#### Storage

To protect the product from the effects of humidity until the package is opened, dry-box storage is recommended. If this is not possible, store the product under the following conditions:

Temperature: 10 to 30°C Humidity: 60% max.

The product is packed in a humidity-proof envelope. Reflow soldering must be done within 48 hours after opening the envelope, during which time the product must be stored under 30°C at 80% maximum humidity.

If it is necessary to store the product after opening the envelope, use dry-box storage or reseal the envelope.

#### **Baking**

If a product has remained packed in a humidity-proof envelope for six months or more, or if more than 48 hours have lapsed since the envelope was opened, bake the product under the following conditions before use:

Reel: 60°C for 24 hours or more Bulk: 80°C for 4 hours or more